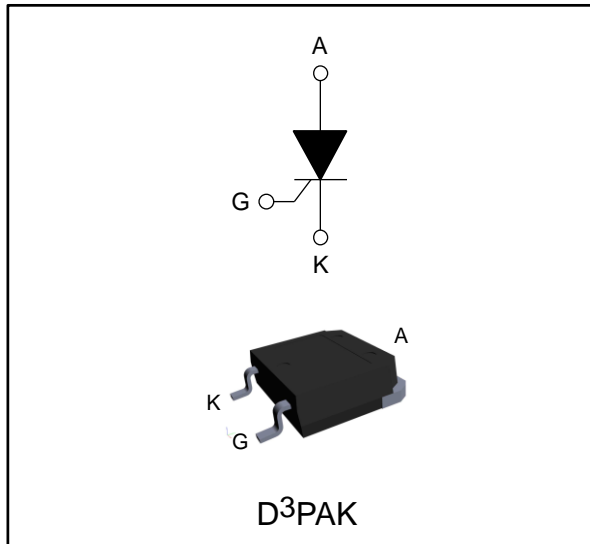


80 A high temperature Thyristor (SCR)

Datasheet - production data



Applications

- AC-DC rectifier controlled bridge
- Motorbike voltage regulator
- Variable speed motor drive
- Battery charging system
- AC solid state relay
- By-pass switch of UPS
- Industrial welding systems
- Motor soft starter

Description

Available in high power package (D³PAK), the device is suitable in applications where power switching ($I_{T(RMS)} = 80\text{ A}$ at $T_C = 130\text{ °C}$) and power dissipation ($V_{TM} = 1.55\text{ V}$ at 160 A) are critical, such as motorbike voltage regulator, by-pass AC switch, controlled rectifier bridge, solid state relay, battery charger, welding equipment and motor driver applications. The TM8050H-8D3 is available in surface mount D³PAK package.

Table 1: Device summary

Symbol	Value
$I_{T(RMS)}$	80 A
V_{DRM}/V_{RRM}	800 V
I_{GT}	50 mA
T_j	150 °C

Features

- High junction temperature: $T_j = 150\text{ °C}$
- Blocking voltage: $V_{DRM} = V_{RRM} = 800\text{ V}$
- Nominal current: $I_{T(RMS)} = 80\text{ A}$
- Gate triggering current: $I_{GT\text{ max.}} = 50\text{ mA}$
- High noise immunity: $dV/dt > 1\text{ kV}/\mu\text{s}$
- Surface mounted device D³PAK
- Increase of thermal margin due to extended T_j up to 150 °C
- Low I_D and I_R in blocking state
- High compact power SMD design

1 Characteristics

Table 2: Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit	
$I_{T(RMS)}$	RMS on-state current (180 ° conduction angle)		80	A	
$I_{T(AV)}$	Average on-state current (180 ° conduction angle)				
I_{TSM}	Non repetitive surge peak on-state current	$t_p = 8.3 \text{ ms}$	731	A	
		$t_p = 10 \text{ ms}$			
I^2t	I^2t value for fusing		2245	A^2s	
V_{RRM} / V_{DRM}	Maximum repetitive symmetric blocking voltage			800	V
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}, tr \leq 100 \text{ ns}$	$f = 50 \text{ Hz}$	$T_j = 25 \text{ °C}$	200	$A/\mu s$
I_{GM}	Peak gate current	$t_p = 20 \mu s$	$T_j = 150 \text{ °C}$	8	A
$P_{G(AV)}$	Average gate power dissipation		$T_j = 150 \text{ °C}$	1	W
V_{RGM}	Maximum peak reverse gate voltage			5	V
T_{stg}	Storage junction temperature range			-40 to +150	°C
T_j	Maximum operating junction temperature			-40 to +150	°C
T_L	Maximum lead temperature during 10 to 30 s duration			245	°C

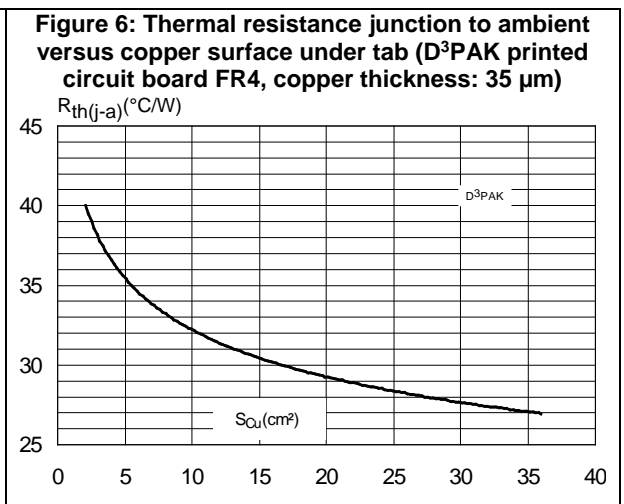
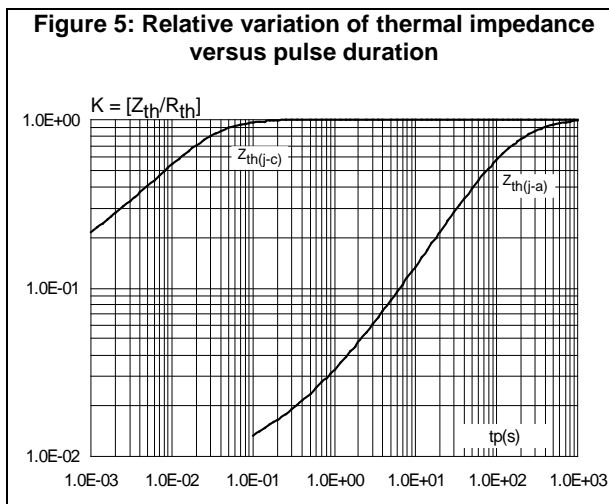
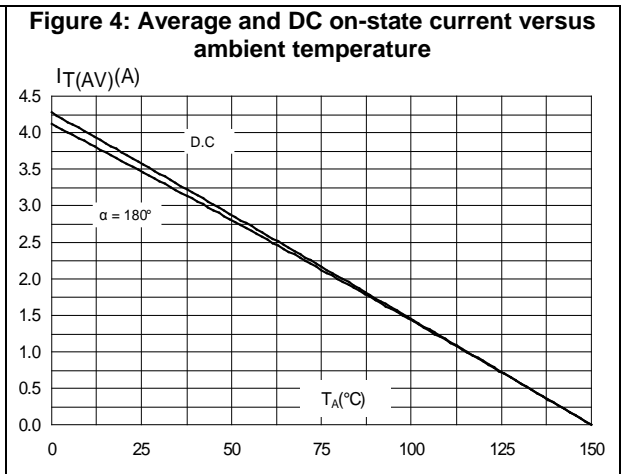
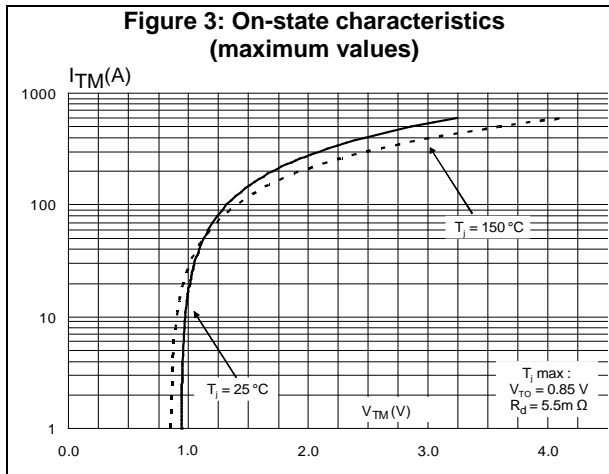
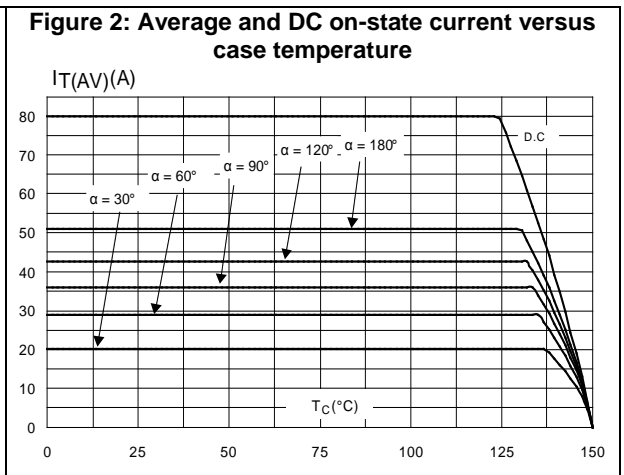
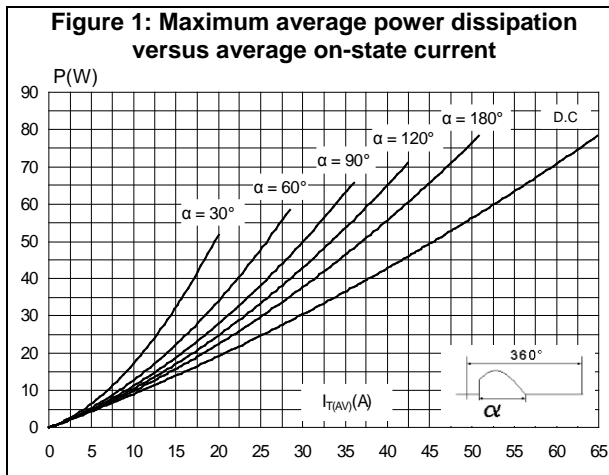
Table 3: Electrical characteristics ($T_j = 25 \text{ °C}$ unless otherwise specified)

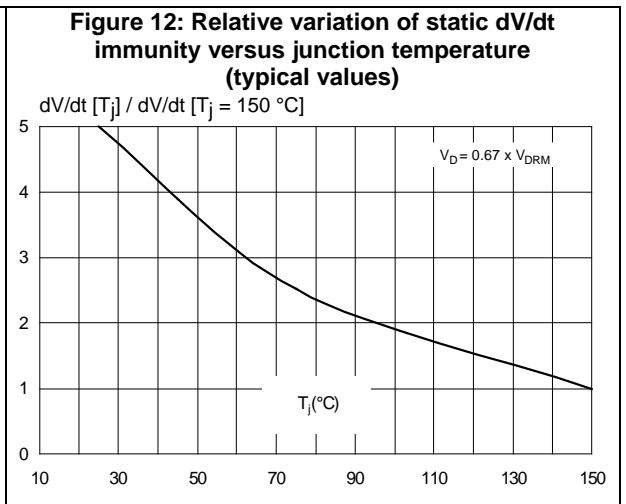
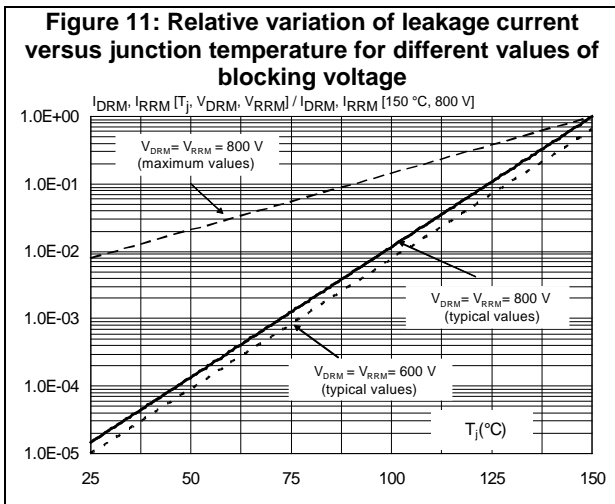
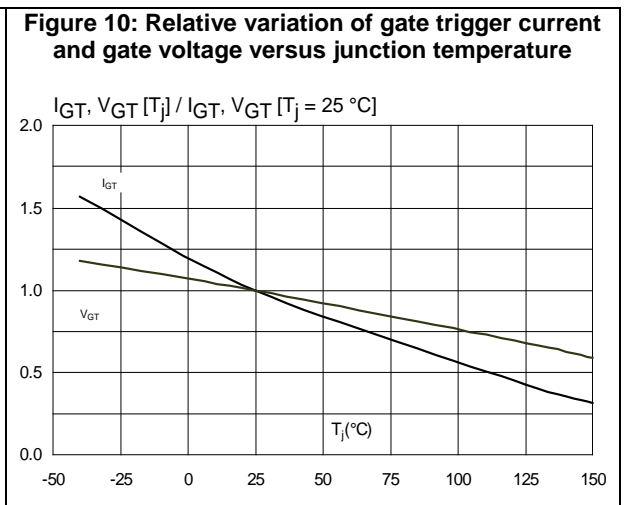
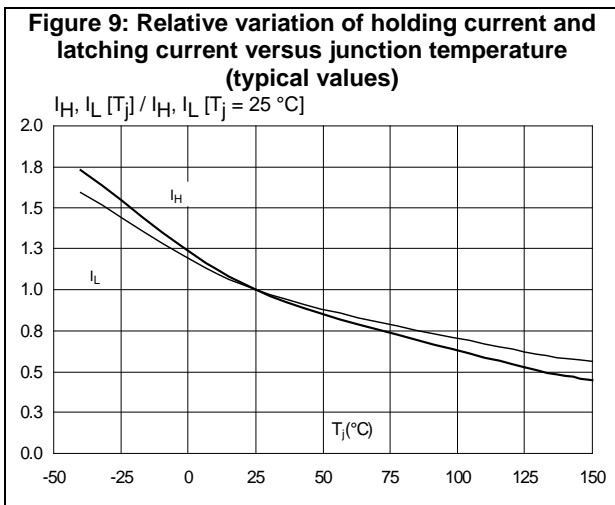
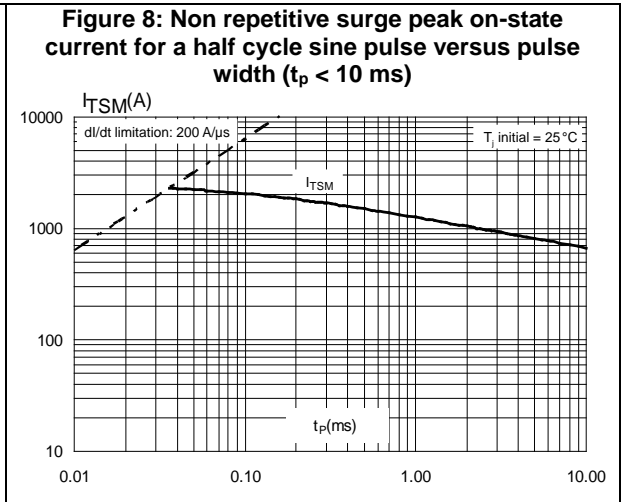
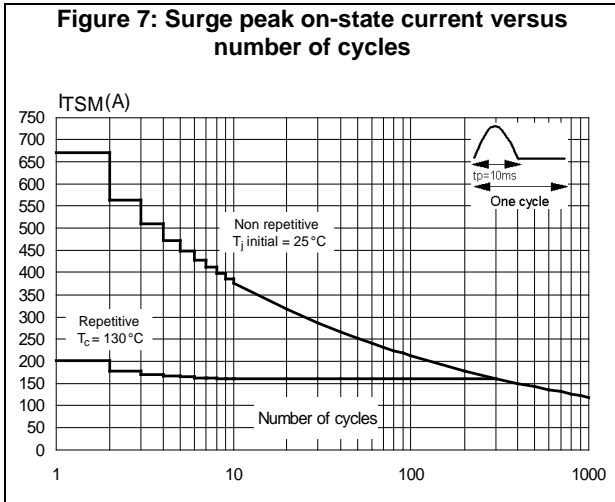
Symbol	Test Conditions		Value	Unit		
I_{GT}	$V_D = 12 \text{ V}, R_L = 33 \Omega$	Min.	2.5	mA		
		Max.	50			
V_{GT}	$V_D = 12 \text{ V}, R_L = 33 \Omega$	Max.	1.5	V		
V_{GD}	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega$	$T_j = 150 \text{ °C}$	Min.	0.2	V	
I_H	$I_T = 500 \text{ mA}, \text{ gate open}$		Max.	100	mA	
I_L	$I_G = 1.2 \times I_{GT}$		Max.	125	mA	
t_{gt}	$I_T = 80 \text{ A}, V_D = V_{DRM}, I_G = 200 \text{ mA}, di_G/dt = 0.2 \text{ A}/\mu s$		Typ.	3	μs	
dV/dt	$V_D = 67 \% V_{DRM}, \text{ gate open}$	$T_j = 150 \text{ °C}$	Min.	1000	$V/\mu s$	
t_q	$I_T = 33 \text{ A}, di_T/dt = 10 \text{ A}/\mu s, V_R = 75 \text{ V}, V_D = 400 \text{ V}, dV_D/dt = 20 \text{ V}/\mu s, t_p = 100 \mu s$	$T_j = 150 \text{ °C}$	Max.	150	μs	
V_{TM}	$I_{TM} = 160 \text{ A}, t_p = 380 \mu s$	$T_j = 25 \text{ °C}$	Max.	1.55	V	
V_{TO}	Threshold voltage		$T_j = 150 \text{ °C}$	Max.	0.85	V
R_D	Dynamic resistance		$T_j = 150 \text{ °C}$	Max.	5.5	$m\Omega$
I_{DRM}	$V_D = V_{DRM} = V_R = V_{RRM} = 800 \text{ V}$	$T_j = 25 \text{ °C}$	Max.	20	μA	
I_{RRM}		$T_j = 150 \text{ °C}$	Max.	2.5	mA	

Table 4: Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case (DC, max.)	D ³ PAK	0.25	°C/W
$R_{th(j-a)}$	Junction to ambient (DC, typ., $S_{cu} = 2.1 \text{ cm}^2$)		40	

1.1 Characteristics (curves)





2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Epoxy meets UL 94,V0
- Lead-free package leads, halogen-free molding resin
- Pre-conditioning moisture sensitivity MSL 1

2.1 D³PAK package information

Figure 13: D³PAK package dimension definitions

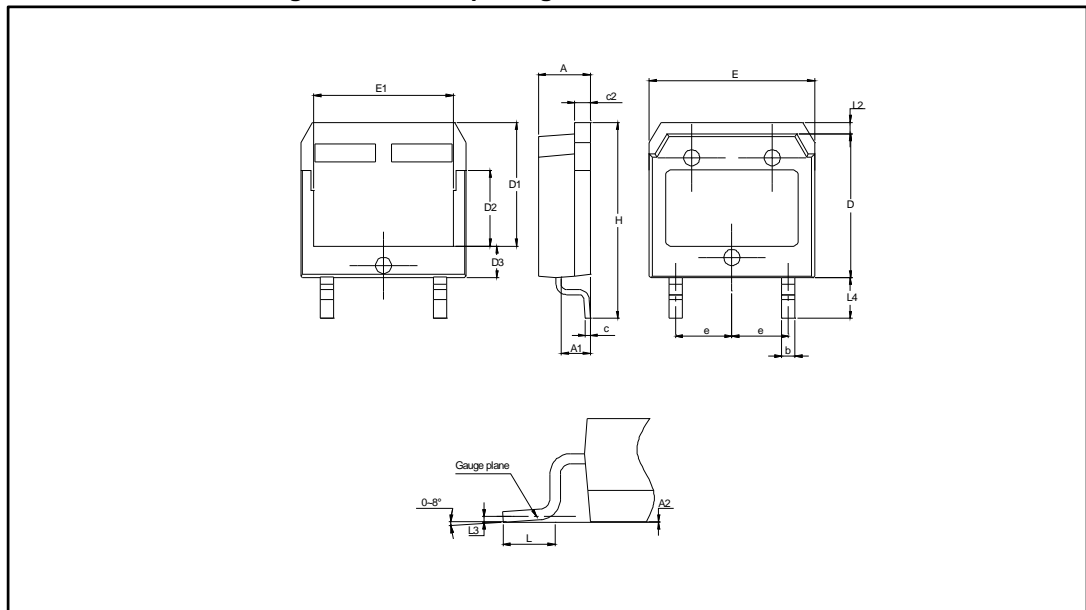


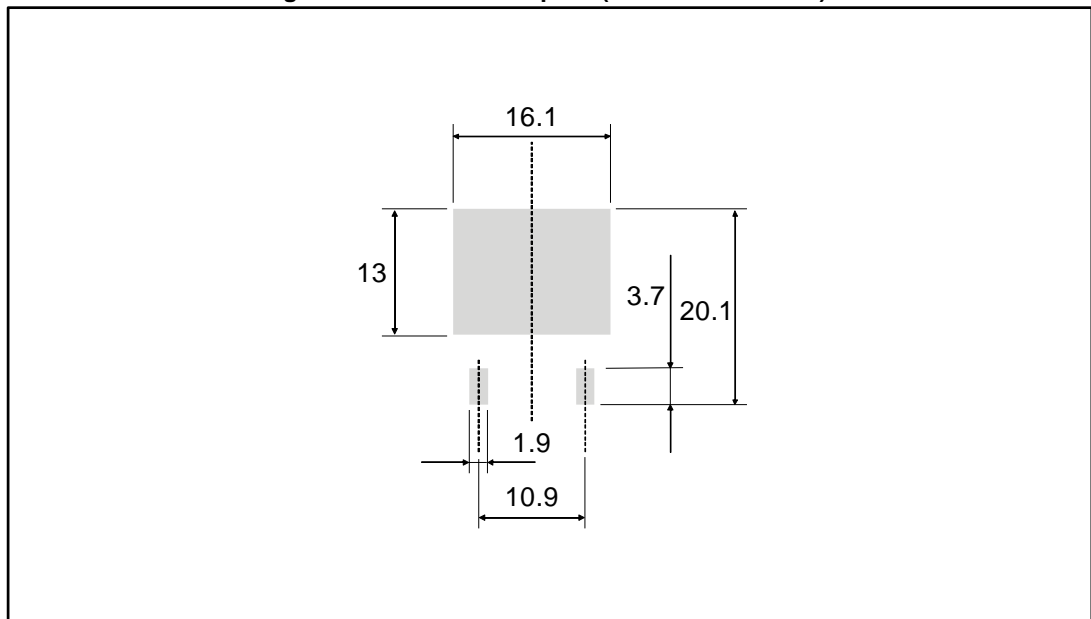
Table 5: D³PAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.90		5.10	0.1929		0.2008
A1	2.70		2.90	0.1063		0.1142
A2	0.02		0.25	0.0008		0.0098
b	1.15		1.45	0.0453		0.0571
c	0.40		0.65	0.0157		0.0256
c2	1.45		1.61	0.0571		0.0634
D	13.80		14.00	0.5433		0.5512
D1	11.80		12.10	0.4646		0.4764
D2	7.50		7.80	0.2953		0.3071
D3	2.90		3.20	0.1142		0.1260
E	15.85		16.05	0.6240		0.6319
E1	13.30		13.60	0.5236		0.5354
e		5.45			0.2146	
H	18.70		19.10	0.7362		0.7520
L	1.70		2.00	0.0669		0.0789
L2	1.00		1.15	0.0394		0.0453
L3		0.25			0.0098	
L4	3.80		4.10	0.1496		0.1614

Notes:

⁽¹⁾Dimension in inches are given for reference only.

Figure 14: Minimum footprint (dimensions in mm)



3 Ordering information

Figure 15: Ordering information scheme

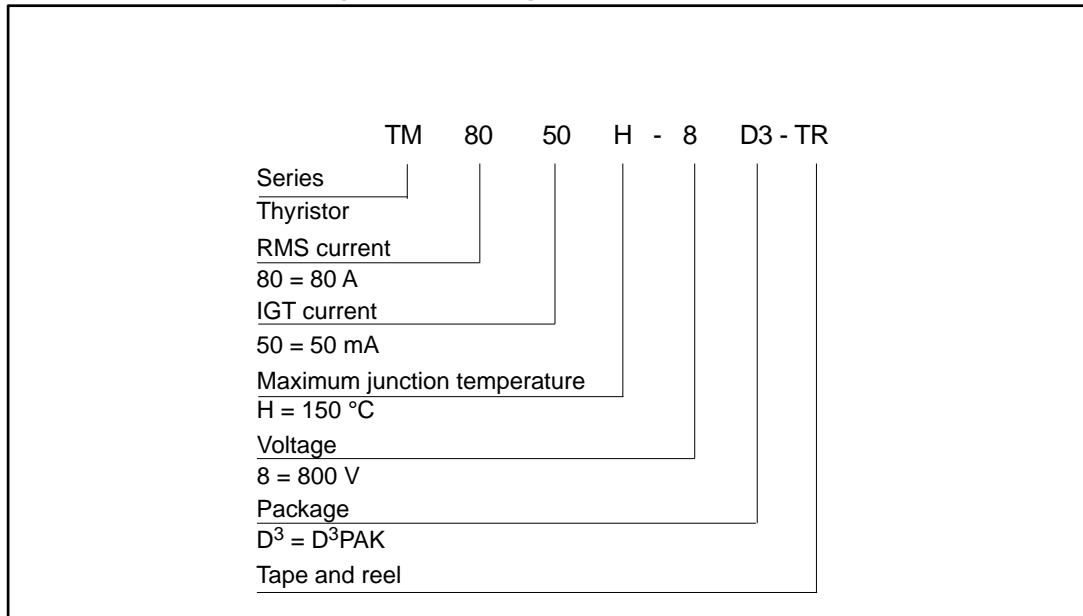


Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
TM8050H-8D3-TR	TM8050H8	D ³ PAK	4.2 g	400	Tape and reel

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
11-Feb-2016	1	Initial release.
01-Apr-2016	2	Updated Table 3: "Electrical characteristics (T _j = 25 °C unless otherwise specified)".
29-Apr-2016	3	Updated Table 4: "Thermal parameters" .

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